

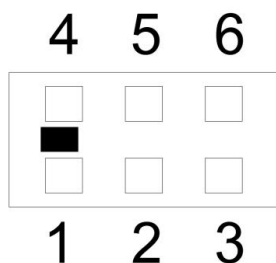
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

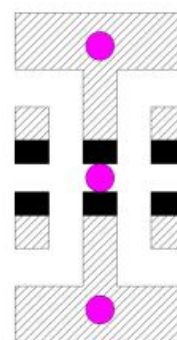
NO.	Parameter	SPC
1	Frequency range	1650-2180 MHz
2	Insertion Loss	0.7 dB max.
3	Attenuation	20 dB min. @ 3350~4360 MHz 40 dB min. @ 5085~6540 MHz
4	Ruture Loss (In BW)	15.0.
5	Port Impedance	50Ω
6	Operation Temperature Range	-40℃ ~ +85℃

Construction



PIN	Connection
1	NC
2	GND
3	NC
4	Output port
5	GND
6	Input port

Mounting Considerations

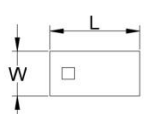
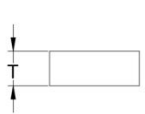
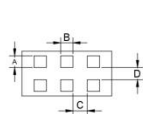


- Land
- ▨ Solder
- Through-hole

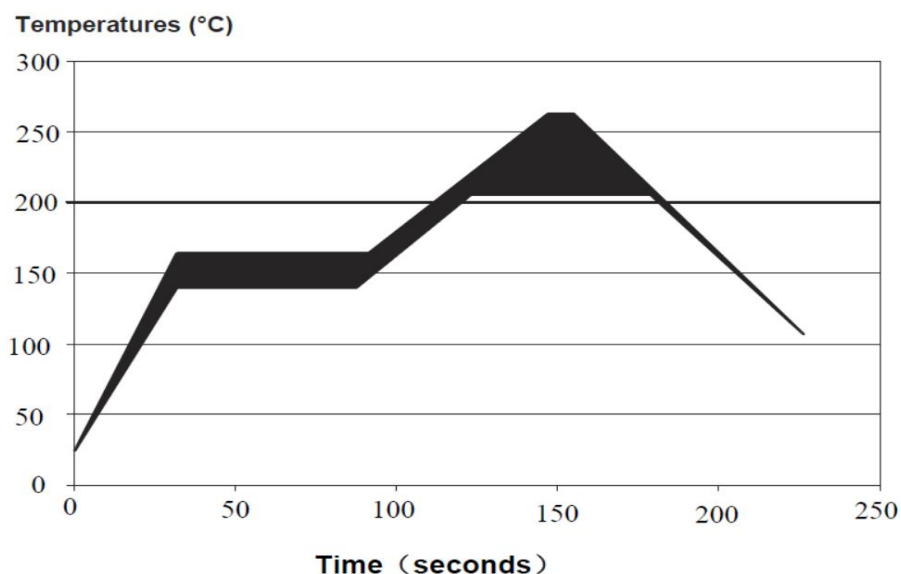
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
TOP VIVE  SIDE VIVE  BOTTOM VIVE 	L	1.0 ± 0.05
	W	0.5 ± 0.05
	T	0.38 ± 0.05
	A	0.125 ± 0.05
	B	0.18 ± 0.05
	C	0.18 ± 0.05
	D	0.15 ± 0.05

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.